

REMARKS

Claim 14 has been objected to in the Office Action. Claim 14 has been amended to correct the noted typographical error.

Claims 18-20 would be allowable if rewritten in independent form to include any base and intervening claims.

Claims 14-17 and 21-26 have been rejected under 35 USC 103(a) as unpatentable over Lake (U.S. Patent No. 5,972,152) in view of Zhang (U.S. Patent No. 6,391,220) and Tanaka (U.S. Patent No. 5,909,009). We note that the Examiner appears to have mistakenly failed to consider claim 27 (see Preliminary Amendment February 28, 2001. However, we have treated claim 27, for purposes of this amendment, as if it has been rejected similar to claim 14. The rejection is respectfully traversed.

Lake discloses a method for fixing a flexible circuit substrate to a processing carrier. In this regard, an adhesive film is used which comprises acrylic, silicon or a silicon acrylic blend. Due to the use of the adhesive film, the flexible circuit substrate can be removed from the processing carrier following processing thereof. Hence, there is no need to employ laser treatment in the method disclosed by Lake. In fact, use of a laser in Lake would be counterproductive or prohibitive in using the method disclosed by Lake. If indeed a laser were directed to the adhesive film in Lake, it would harden the adhesive film, making it impossible to remove the flexible circuit from the processing center.

Additionally, even assuming *arguendo* that Zhang and/or Tanaka disclose such laser treatment, one having ordinary skill in the art would not have been motivated to combine the references. Specifically, applying a laser treatment from Zhang and/or Tanaka for use with the method in Lake would still render the combination useless, as described above. Hence, even a combination of references fails to disclose the claimed invention.

Since the recited structure and method are not disclosed by the applied prior art, either alone or in combination, claims 14-27 are patentable.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made".

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

Entry of this amendment after final is appropriate since it removes issues for appeal and only amends claim 14 to correct a typographical error.

In the unlikely event that the transmittal letter is separated from this document and the Patent Office determines that an extension and/or other relief is required, Applicant(s) petition(s) for any required relief including extensions of time and authorizes the Assistant Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952 referencing docket no. 449122018000.

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Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims

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Please amend claim 14 to read:

14. (Currently Amended) A method for manufacturing flexible metallic fine structures on a thin base layer made of a flexible organic material, comprising:

providing an auxiliary bearer made of a material that is at least largely transparent to laser radiation;

applying the base layer onto the auxiliary bearer;

producing a flexible metallic fine structure on the base layer; and

detaching the base layer ~~from~~ from the auxiliary bearer by projecting laser radiation from a laser through the auxiliary bearer onto the base layer.